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LED ARRAY



Lead-Free Parts

LA93B/Y-1-PF

DATA SHEET

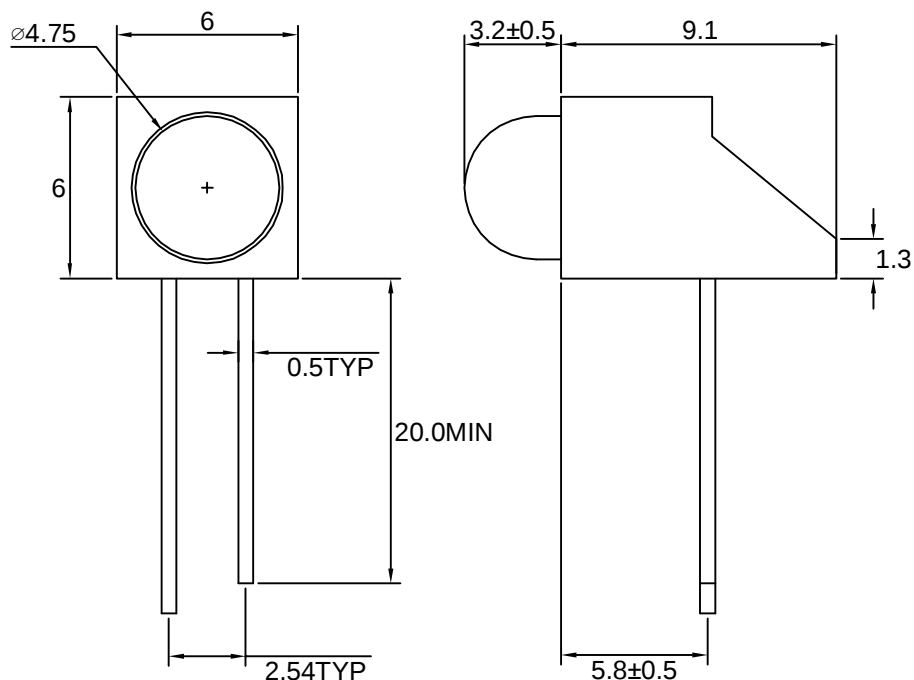
DOC. NO : QW0905-LA93B/Y-1-PF

REV. : A

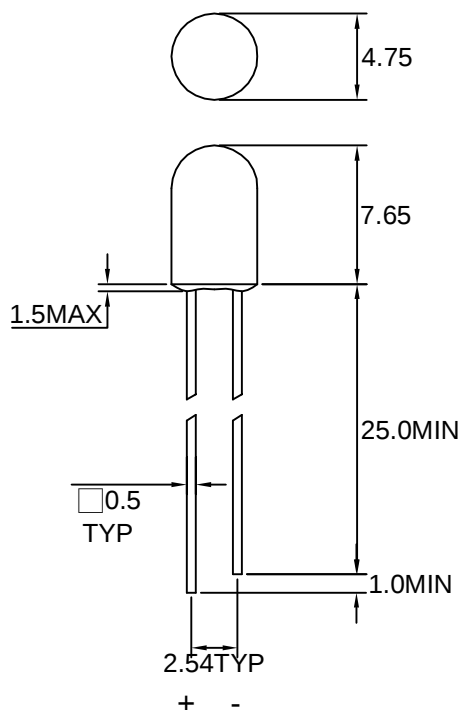
DATE : 14 - Oct. - 2014



Package Dimensions



LY3130-PF



Note : 1.All dimension are in millimeter tolerance is ± 0.25 mm unless otherwise noted.
 2.Specifications are subject to change without notice.

Absolute Maximum Ratings at Ta=25 °C

Parameter	Symbol	Ratings	UNIT
		Y	
Forward Current	I _F	20	mA
Peak Forward Current Duty 1/10@10KHz	I _{FP}	80	mA
Power Dissipation	PD	60	mW
Reverse Current @5V	I _r	10	μA
Operating Temperature	T _{opr}	-20 ~ +85	°C
Storage Temperature	T _{stg}	-30 ~ +100	°C

Typical Electrical & Optical Characteristics (Ta=25 °C)

PART NO	MATERIAL	COLOR		Peak wave length λ Pnm	Spectral halfwidth Δ λ nm	Forward voltage @20mA(V)		Luminous intensity @10mA(mcd)		Viewing angle 2θ 1/2 (deg)
		Emitted	Lens			Min.	Max.	Min.	Typ.	
LA93B/Y-1-PF	GaAsP/GaP	Yellow	Yellow Diffused	585	35	1.7	2.6	20	30	46

Note : 1.The forward voltage data did not including ±0.1V testing tolerance.
2. The luminous intensity data did not including ±15% testing tolerance.

Brightness Code For Standard LED Lamps

Bin Code

Group	Luminous Intensity(mcd) at 10 mA	
	Min.	Max.
A11	20	30
A12	30	45
A13	45	65
A14	65	100
A15	100	150
A16	150	200

Color Code

Y CHIP

Group	Wave length(nm) at 10 mA	
	Min.	Max.
15	585	587
16	587	589
17	589	592
18	592	595

Typical Electro-Optical Characteristics Curve

Y CHIP

Fig.1 Forward current vs. Forward Voltage

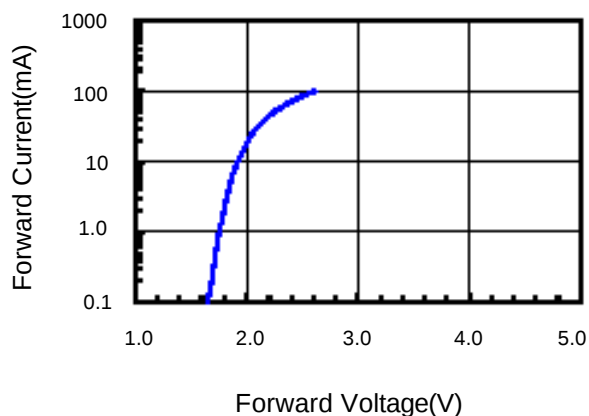


Fig.2 Relative Intensity vs. Forward Current

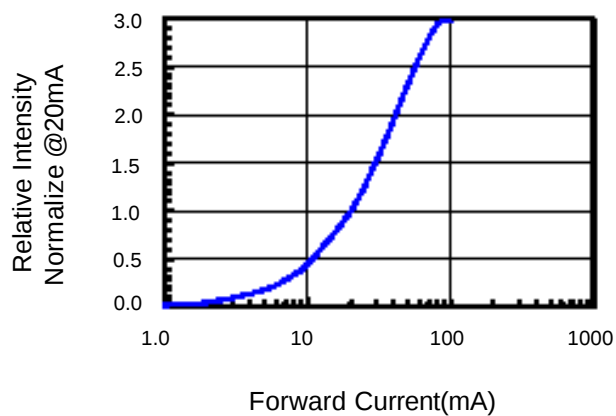


Fig.3 Forward Voltage vs. Temperature

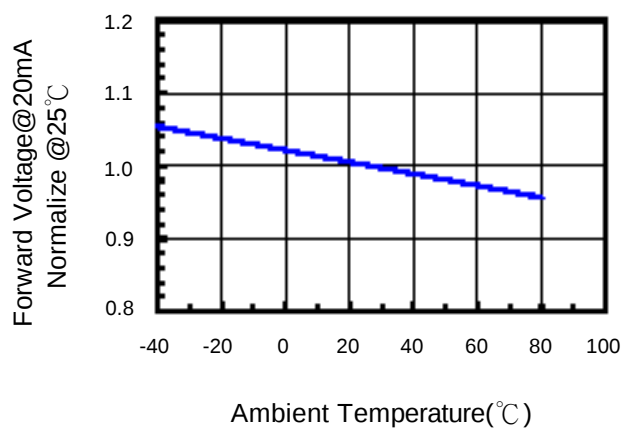


Fig.4 Relative Intensity vs. Temperature

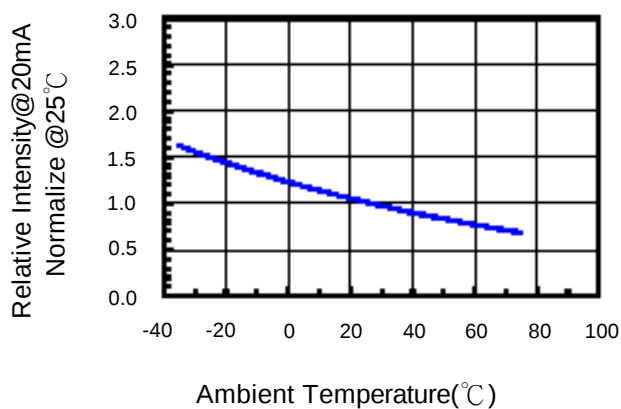
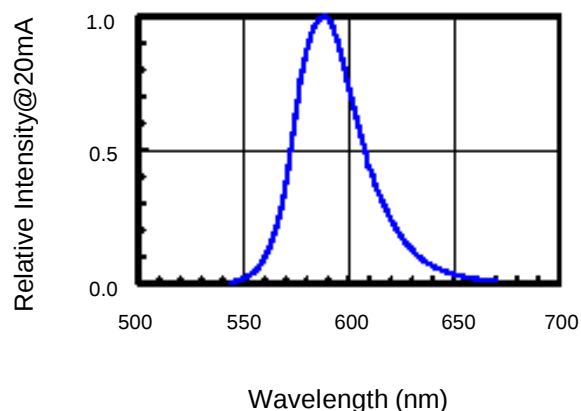


Fig.5 Relative Intensity vs. Wavelength



Soldering Condition(Pb-Free)**1.Iron:**

Soldering Iron:30W Max

Temperature 350° C Max

Soldering Time:3 Seconds Max(One Time)

Distance:2mm Min(From solder joint to case)

2.Wave Soldering Profile

Dip Soldering

Preheat: 120° C Max

Preheat time: 60seconds Max

Ramp-up

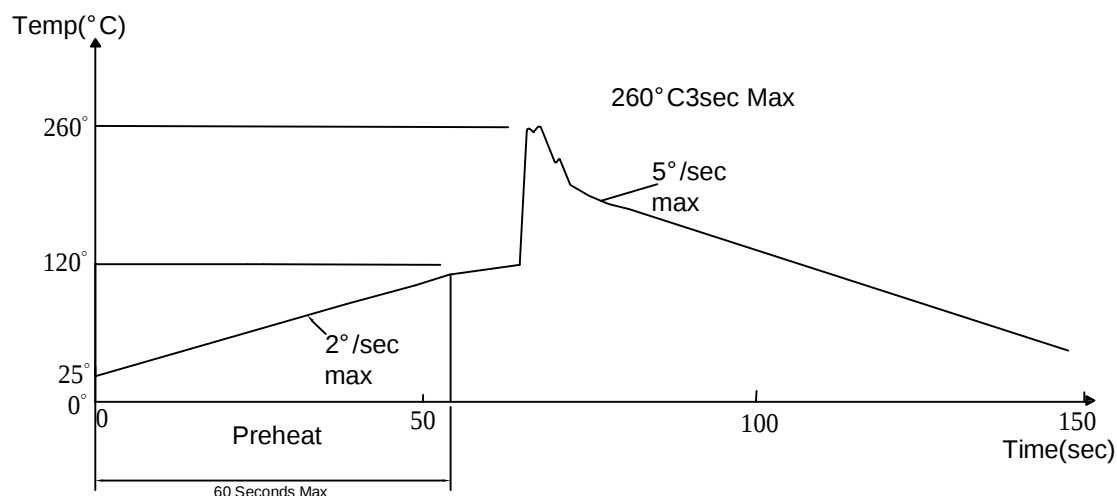
2° C/sec(max)

Ramp-Down:-5° C/sec(max)

Solder Bath:260° C Max

Dipping Time:3 seconds Max

Distance:2mm Min(From solder joint to case)



Note: 1.Wave solder should not be made more than one time.

2.You can just only select one of the soldering conditions as above.

Reliability Test:

Test Item	Test Condition	Description	Reference Standard
Operating Life Test	1.Under Room Temperature 2.If=20mA 3.t=1000 hrs (-24hrs, +72hrs)	This test is conducted for the purpose of determining the resistance of a part in electrical and thermal stressed.	MIL-STD-750: 1026 MIL-STD-883: 1005 JIS C 7021: B-1
High Temperature Storage Test	1.Ta=105 °C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of high temperature for hours.	MIL-STD-883:1008 JIS C 7021: B-10
Low Temperature Storage Test	1.Ta=-40 °C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of low temperature for hours.	JIS C 7021: B-12
High Temperature High Humidity Test	1.Ta=65 °C±5°C 2.RH=90 %~95% 3.t=240hrs ±2hrs	The purpose of this test is the resistance of the device under tropical for hours.	MIL-STD-202:103B JIS C 7021: B-11
Thermal Shock Test	1.Ta=105 °C±5°C & -40 °C±5°C (10min) (10min) 2.total 10 cycles	The purpose of this is the resistance of the device to sudden extreme changes in high and low temperature.	MIL-STD-202: 107D MIL-STD-750: 1051 MIL-STD-883: 1011
Solder Resistance Test	1.T.Sol=260 °C±5°C 2.Dwell time= 10 ±1sec.	This test intended to determine the thermal characteristic resistance of the device to sudden exposures at extreme changes in temperature when soldering the lead wire.	MIL-STD-202: 210A MIL-STD-750: 2031 JIS C 7021: A-1
Solderability Test	1.T.Sol=245 °C±5°C 2.Dwell time=5 ±1sec	This test intended to see soldering well performed or not.	MIL-STD-202: 208D MIL-STD-750: 2026 MIL-STD-883: 2003 JIS C 7021: A-2